

FEATURES

- Member of the Texas Instruments Widebus™ Family
- UBE™ (Universal Bus Exchanger) Allows Synchronous Data Exchange
- Operates From 1.65 V to 3.6 V
- Max t_{pd} of 5.1 ns at 3.3 V
- ± 24 -mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Performance Tested Per JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

This 9-bit, 4-port universal bus exchanger is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16409 allows synchronous data exchange between four different buses. Data flow is controlled by the select (SEL0–SEL4) inputs. A data-flow state is stored on the rising edge of the clock (CLK) input if the select-enable (SELEN) input is low. Once a data-flow state has been established, data is stored in the flip-flop on the rising edge of CLK if SELEN is high.

The data-flow control logic is designed to allow glitch-free data transmission.

When preset (\overline{PRE}) transitions high, the outputs are disabled immediately, without waiting for a clock pulse. To leave the high-impedance state, both \overline{PRE} and SELEN must be low, and a clock pulse must be applied.

To ensure the high-impedance state during power up or power down, \overline{PRE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

DGG OR DL PACKAGE
(TOP VIEW)

\overline{PRE}	1	56	CLK
SEL0	2	55	\overline{SELEN}
1A1	3	54	1B1
GND	4	53	GND
1A2	5	52	1B2
1A3	6	51	1B3
V_{CC}	7	50	V_{CC}
1A4	8	49	1B4
1A5	9	48	1B5
1A6	10	47	1B6
GND	11	46	GND
1A7	12	45	1B7
1A8	13	44	1B8
1A9	14	43	1B9
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
V_{CC}	22	35	V_{CC}
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
2A9	26	31	2B9
SEL1	27	30	SEL4
SEL2	28	29	SEL3

ORDERING INFORMATION

T_A	PACKAGE (1)		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	SSOP - DL	Tube	SN74ALVCH16409DL	ALVCH16409
		Tape and reel	SN74ALVCH16409DLR	
	TSSOP - DGG	Tape and reel	SN74ALVCH16409DGGR	ALVCH16409

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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SN74ALVCH16409
9-BIT, 4-PORT UNIVERSAL BUS EXCHANGER
WITH 3-STATE OUTPUTS

SCES022G—JULY 1995—REVISED OCTOBER 2004

FUNCTION TABLES

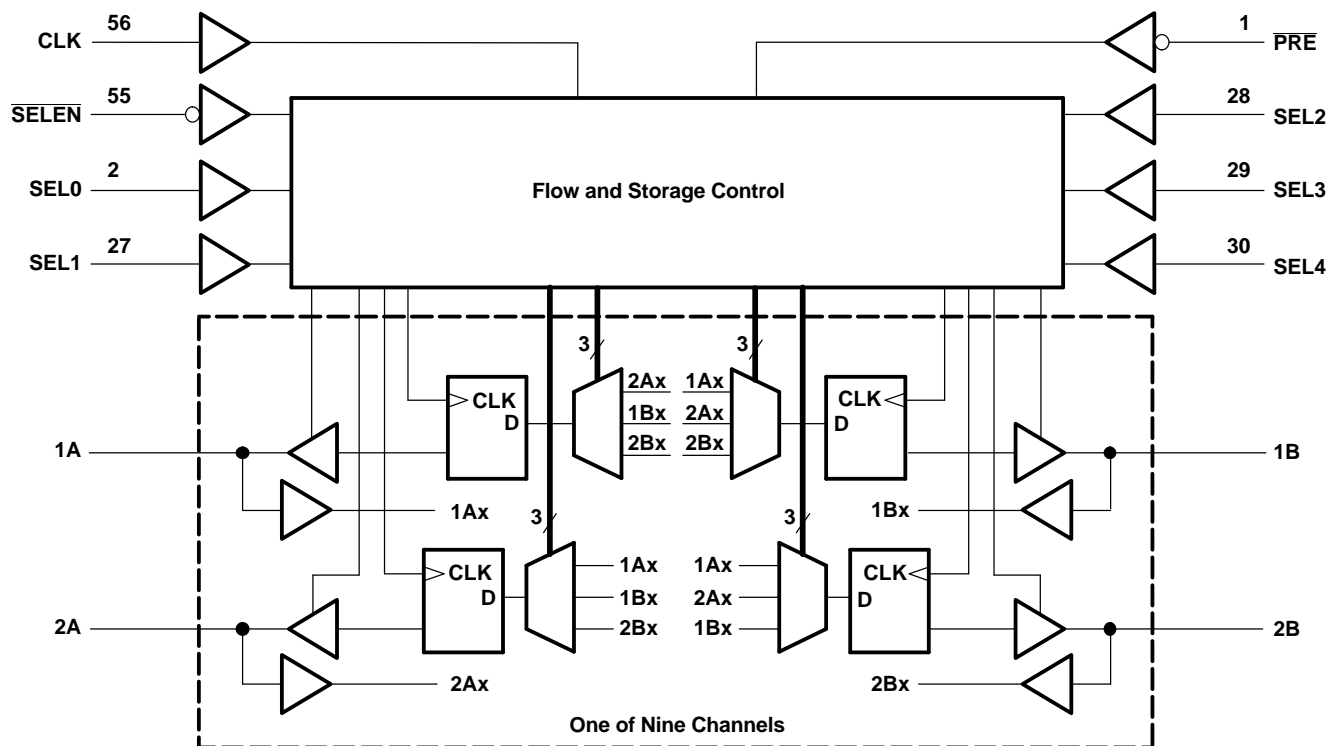
INPUTS		OUTPUT RECEIVE PORT
CLK	SEND PORT	
X	X	B ₀ ⁽¹⁾
X	L	L
X	H	H
↑	L	L
↑	H	H
H	X	B ₀ ⁽¹⁾
L	X	B ₀ ⁽¹⁾

(1) Output level before the indicated steady-state input conditions were established

DATA-FLOW CONTROL

INPUTS								DATA FLOW
PRE	SELEN	CLK	SEL0	SEL1	SEL2	SEL3	SEL4	
H	X	X	X	X	X	X	X	All outputs disabled
L	H	↑	X	X	X	X	X	No change
L	L	↑	0	0	0	0	0	None, all I/Os off
L	L	↑	0	0	0	0	1	Not used
L	L	↑	0	0	0	1	0	Not used
L	L	↑	0	0	0	1	1	Not used
L	L	↑	0	0	1	0	0	Not used
L	L	↑	0	0	1	0	1	Not used
L	L	↑	0	0	1	1	0	Not used
L	L	↑	0	0	1	1	1	Not used
L	L	↑	0	1	0	0	0	2A to 1A and 1B to 2B
L	L	↑	0	1	0	0	1	2A to 1A
L	L	↑	0	1	0	1	0	2B to 1B
L	L	↑	0	1	0	1	1	2A to 1A and 2B to 1B
L	L	↑	0	1	1	0	0	1A to 2A and 1B to 2B
L	L	↑	0	1	1	0	1	1A to 2A
L	L	↑	0	1	1	1	0	1B to 2B
L	L	↑	0	1	1	1	1	1A to 2A and 2B to 1B
L	L	↑	1	0	0	0	0	1A to 1B and 2B to 2A
L	L	↑	1	0	0	0	1	1A to 1B
L	L	↑	1	0	0	1	0	2A to 2B
L	L	↑	1	0	0	1	1	1A to 1B and 2A to 2B
L	L	↑	1	0	1	0	0	1B to 1A and 2A to 2B
L	L	↑	1	0	1	0	1	1B to 1A
L	L	↑	1	0	1	1	0	2B to 2A
L	L	↑	1	0	1	1	1	1B to 1A and 2B to 2A
L	L	↑	1	1	0	0	0	2B to 1A and 2A to 1B
L	L	↑	1	1	0	0	1	1B to 2A
L	L	↑	1	1	0	1	0	2B to 1A
L	L	↑	1	1	0	1	1	2B to 1A and 1B to 2A
L	L	↑	1	1	1	0	0	1A to 2B and 1B to 2A
L	L	↑	1	1	1	0	1	1A to 2B
L	L	↑	1	1	1	1	0	2A to 1B
L	L	↑	1	1	1	1	1	1A to 2B and 2A to 1B

LOGIC DIAGRAM (POSITIVE LOGIC)



SN74ALVCH16409

9-BIT, 4-PORT UNIVERSAL BUS EXCHANGER WITH 3-STATE OUTPUTS

SCES022G–JULY 1995–REVISED OCTOBER 2004

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}	Supply voltage range		-0.5	4.6	V
V_I	Input voltage range	Except I/O ports ⁽²⁾	-0.5	4.6	V
		I/O ports ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	
V_O	Output voltage range ⁽²⁾⁽³⁾		-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		-50	mA
I_{OK}	Output clamp current	$V_O < 0$		-50	mA
I_O	Continuous output current			± 50	mA
	Continuous current through each V_{CC} or GND			± 100	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾	DGG package		64	°C/W
		DL package		56	
T_{stg}	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

			MIN	MAX	UNIT
V_{CC}	Supply voltage		1.65	3.6	V
V_{IH}	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
V_{IL}	Low-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 1.65 \text{ V}$		-4	mA
		$V_{CC} = 2.3 \text{ V}$		-12	
		$V_{CC} = 2.7 \text{ V}$		-12	
		$V_{CC} = 3 \text{ V}$		-24	
I_{OL}	Low-level output current	$V_{CC} = 1.65 \text{ V}$		4	mA
		$V_{CC} = 2.3 \text{ V}$		12	
		$V_{CC} = 2.7 \text{ V}$		12	
		$V_{CC} = 3 \text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
T_A	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{OH}		I _{OH} = -100 µA	1.65 V to 3.6 V	V _{CC} - 0.2			V
		I _{OH} = -4 mA	1.65 V	1.2			
		I _{OH} = -6 mA	2.3 V	2			
		I _{OH} = -12 mA	2.3 V	1.7			
			2.7 V	2.2			
			3 V	2.4			
		I _{OH} = -24 mA	3 V	2			
V _{OL}		I _{OL} = 100 µA	1.65 V to 3.6 V			0.2	V
		I _{OL} = 4 mA	1.65 V			0.45	
		I _{OL} = 6 mA	2.3 V			0.4	
		I _{OL} = 12 mA	2.3 V			0.7	
			2.7 V			0.4	
		I _{OL} = 24 mA	3 V			0.55	
I _I		V _I = V _{CC} or GND	3.6 V			±5	µA
I _{I(hold)}		V _I = 0.58 V	1.65 V	25			µA
		V _I = 1.07 V	1.65 V	-25			
		V _I = 0.7 V	2.3 V	45			
		V _I = 1.7 V	2.3 V	-45			
		V _I = 0.8 V	3 V	75			
		V _I = 2 V	3 V	-75			
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V			±500	
I _{OZ} ⁽³⁾		V _O = V _{CC} or GND	3.6 V			±10	µA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6 V			40	µA
ΔI _{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			750	µA
C _i	Control inputs	V _I = V _{CC} or GND	3.3 V	4			pF
C _{io}	A or B ports	V _O = V _{CC} or GND	3.3 V	8			pF

(1) All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I_{OZ} includes the input leakage current.

SN74ALVCH16409

9-BIT, 4-PORT UNIVERSAL BUS EXCHANGER WITH 3-STATE OUTPUTS

SCES022G–JULY 1995–REVISED OCTOBER 2004

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} = 1.8 V		V _{CC} = 2.5 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX		
f _{clock}	Clock frequency		(1)		120		120		120		MHz
t _w	Pulse duration, CLK high or low		(1)		4.2		4.2		3		ns
t _{su}	Setup time	A or B before CLK↑	(1)		1.9		1.9		1.4		ns
		SEL before CLK↑	(1)		5.1		4.2		3.5		
		$\overline{\text{SELEN}}$ before CLK↑	(1)		2.5		2.5		1.8		
		$\overline{\text{PRE}}$ before CLK↑	(1)		1		1		0.7		
t _h	Hold time	A or B after CLK↑	(1)		0.8		0.8		1		ns
		SEL after CLK↑	(1)		0		0		0		
		$\overline{\text{SELEN}}$ after CLK↑	(1)		0.5		0.5		0.8		

(1) This information was not available at the time of publication.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$		$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			(1)		120		120		120		MHz
t_{pd}	CLK	A or B	(1)		1.5	6	5.7		1.5	5.1	ns
t_{en}	CLK	A or B	(1)		2.4	6.9	6.3		2	5.7	ns
t_{dis}	CLK	A or B	(1)		2.3	7.1	6		2	5.7	ns
	$\overline{\text{PRE}}$		(1)		2.8	7.5	6.5		2.5	6.1	

(1) This information was not available at the time of publication.

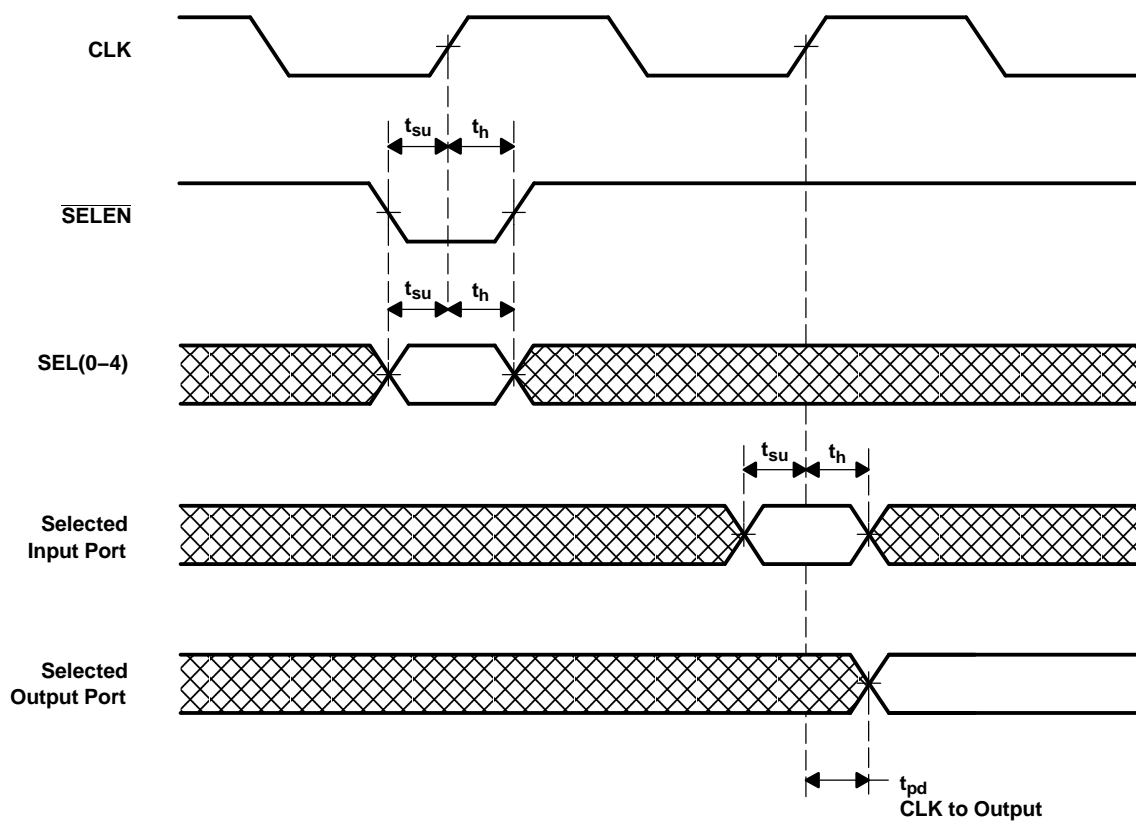
OPERATING CHARACTERISTICS

$T_A = 25^\circ\text{C}$

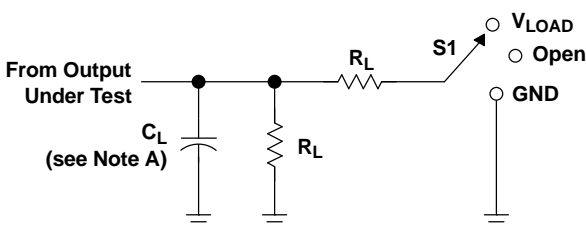
PARAMETER			TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
				TYP	TYP	TYP	
C_{pd}	Power dissipation capacitance per exchanger	All outputs enabled	$C_L = 50\text{ pF}, f = 10\text{ MHz}$	(1)	60	60	pF
		All outputs disabled		(1)	60	60	

(1) This information was not available at the time of publication.

TIMING DIAGRAM



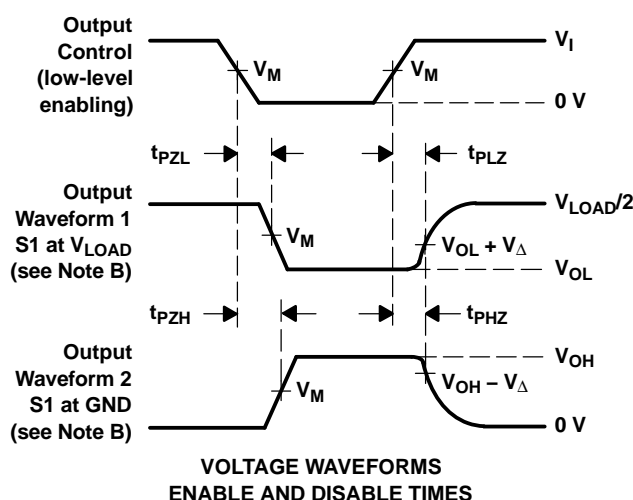
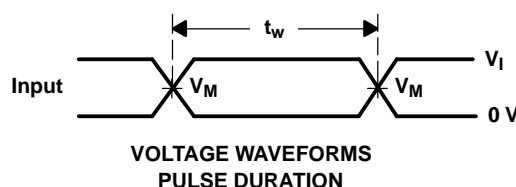
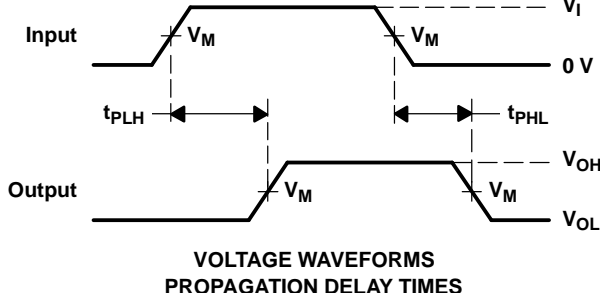
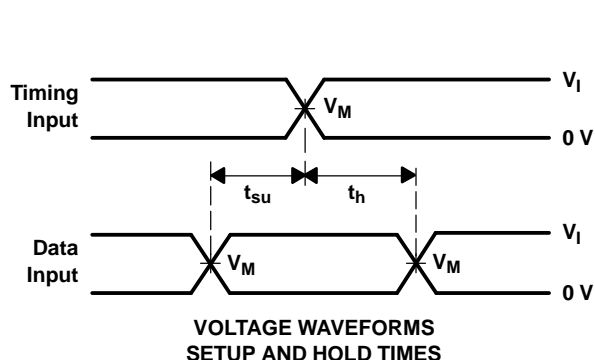
PARAMETER MEASUREMENT INFORMATION



LOAD CIRCUIT

TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	V_{LOAD}
t_{PHZ}/t_{PZH}	GND

V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
74ALVCH16409DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16409	Samples
SN74ALVCH16409DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16409	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

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Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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DL (R-PDSO-G56)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MO-118

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